



FACTS & FIGURES

NEWAYS MICRO ELECTRONICS B.V.



> YOUR LIFECYCLE PARTNER

> TECHNOLOGY SOLUTION PROVIDER

> DESIGN FOR EXCELLENCE

FIGURES

FOUNDED		1980
EMPLOYEES		75

QUALITY STANDARDS

ISO 9001	BUSINESS PROCESSES
ISO 13485	MEDICAL DEVICES
ISO 14001	ENVIRONMENT
IATF 16949	AUTOMOTIVE
AQAP 2110	DEFENCE

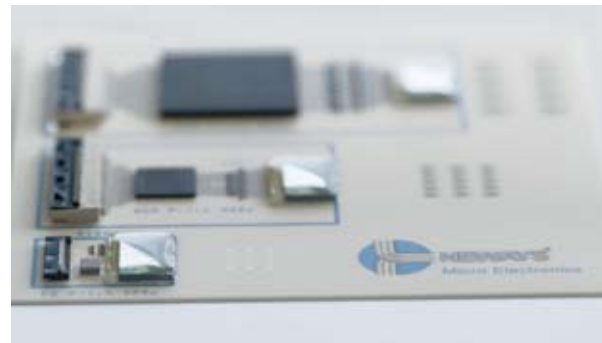
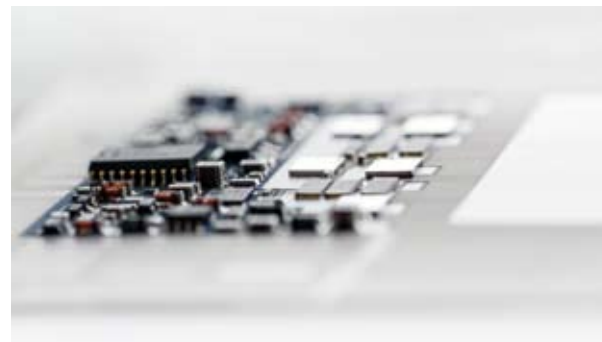
COMPETENCES

COB	THICK FILM	ADVANCED PATTERNING TECHNIQUES	MICRO ASSEMBLY
LIFECYCLE PARTNERSHIP			

YOUR BENEFITS

- > High reliability
- > Miniaturization
- > High thermal conduction
- > High environmental temperature
- > High frequency range
- > No outgassing

WORLD LEADING TECHNOLOGY FINE-LINE AND POWER



STANDARD THICK-FILM PERFORMANCE

> Line & space: 250 µm

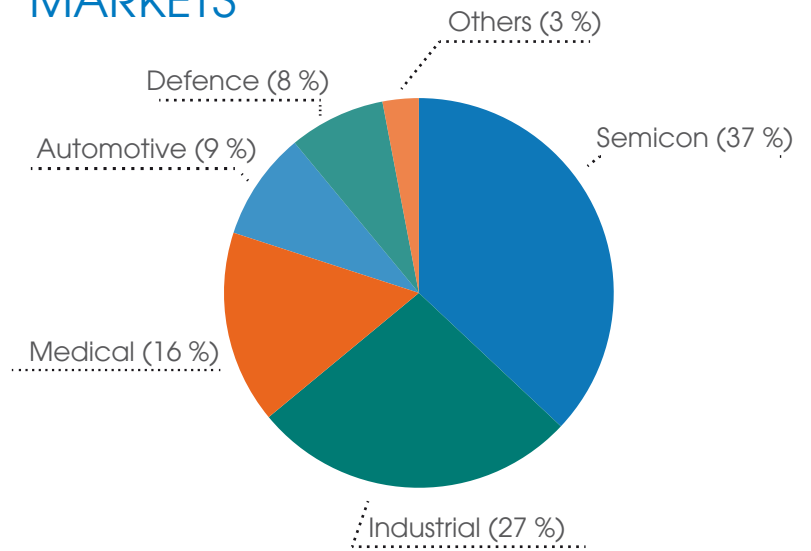
OPTIMIZED THICK-FILM CAPABILITIES OF NEWAYS

> Line & space: 100 µm

ROADMAP OF NEWAYS

> Line & space: 25 µm

MARKETS



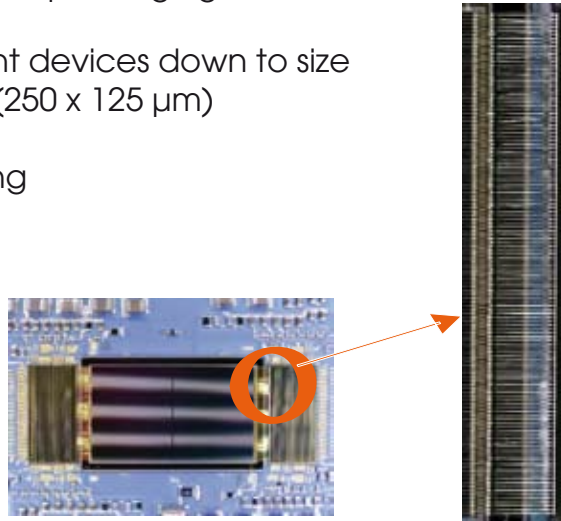
COST EFFECTIVE DOWN SIZING



> YOUR LIFECYCLE PARTNER

MICRO ELECTRONICS ASSEMBLY

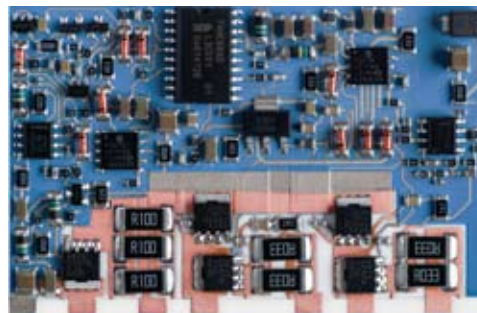
- > Fine-pitch chip and wirebonding (50 µm)
- > Opto-electronic packaging
- > Surface mount devices down to size 008004/0201m (250 x 125 µm)
- > Wafer handling



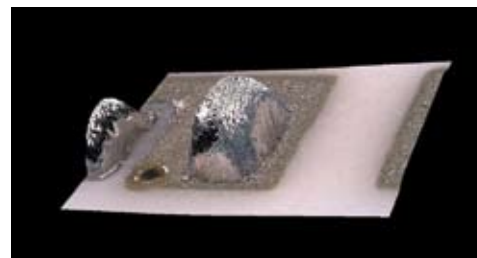
> TECHNOLOGY SOLUTION PROVIDER

INNOVATION ON CERAMIC

- > Research and development of processes and materials
- > Multiple carriers (Al₂O₃, AlN, SiNx, glass, quartz, ...)
- > Innovative technology solutions
 - Electroplating
 - Lithography
 - Laser patterning
 - 3D stencil printing



Patterned copper plating on thick film hybrid for power application



> DESIGN FOR EXCELLENCE

HYBRID TOTAL SOLUTION PROVIDER

- > Co-development, design, testing and assembly of micro electronic products
- > Feasibility and failure analysis



Cleanroom ISO 6 facility